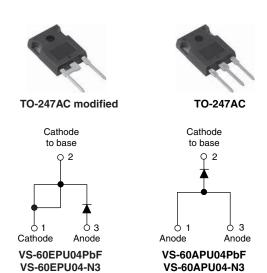


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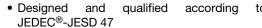
Ultrafast Soft Recovery Diode, 60 A FRED Pt®



PRODUCT SUMMARY	
Package	TO-247AC modified (2 pins), TO-247AC
I _{F(AV)}	60 A
V_{R}	400 V
V _F at I _F	0.87 V
t _{rr} typ.	See Recovery table
T_J max.	175 °C
Diode variation	Single die

FEATURES

- Ultrafast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature



 Material categorization: for definitions of compliance please see www.vishav.com/doc?99912





ROHS COMPLIANT HALOGEN FREE

BENEFITS

- Reduced RFI and EMI
- Higher frequency operation
- · Reduced snubbing
- Reduced parts count

DESCRIPTION / APPLICATIONS

These diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems.

The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for HF welding, power converters and other applications where switching losses are not significant portion of the total losses.

ABSOLUTE MAXIMUM RATINGS										
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS						
Cathode to anode voltage	V_R		400	V						
Continuous forward current	I _{F(AV)}	T _C = 127 °C	60							
Single pulse forward current	I _{FSM}	T _C = 25 °C	600	Α						
Maximum repetitive forward current	I _{FRM}	Square wave, 20 kHz	120							
Operating junction and storage temperatures	T _J , T _{Stg}		-55 to +175	°C						

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Breakdown voltage, blocking voltage	V _{BR} , V _R	Ι _R = 100 μΑ	400	-	-				
Forward voltage	ye V _F	I _F = 60 A	-	1.05	1.25	V			
		I _F = 60 A, T _J = 175 °C	-	0.87	1.03				
		I _F = 60 A, T _J = 125 °C	-	0.93	1.10				
Poverse leekage ourrent	ı	$V_R = V_R$ rated	-	-	50	μA			
Reverse leakage current	I _R	$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-	-	2	mA			
Junction capacitance	C _T	V _R = 400 V	-	50	-	pF			
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	3.5	-	nΗ			



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DYNAMIC RECOVERY CHARACTERISTICS (T _C = 25 °C unless otherwise specified)										
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS				
	t _{rr}	$I_F = 1 A, dI_F/dt = 20$	$I_F = 1 \text{ A}, dI_F/dt = 200 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$			60				
Reverse recovery time		T _J = 25 °C		-	85	-	ns A nC			
		T _J = 125 °C		-	145	-				
Dools recovery as week	I _{RRM}	T _J = 25 °C	$I_F = 60 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$	-	8.8	-				
Peak recovery current		T _J = 125 °C	$V_{\rm R} = 200 \text{ V}$	-	15.4	-				
Daviera management alberta	Q _{rr}	T _J = 25 °C		-	375	-				
Reverse recovery charge		T _J = 125 °C		ı	1120	-				

THERMAL - MECHANICAL SPECIFICATIONS									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Thermal resistance, junction to case	R _{thJC}		-	-	0.70	K/W			
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.2	-	FC/ VV			
Weight			-	5.5	-	g			
vveignt			-	0.2	-	oz.			
Mounting torque			1.2 (10)	-	2.4 (20)	N · m (lbf · in)			
		Case style TO-247AC modified	60EPU04						
Marking device		Case style TO-247AC		60APU04					

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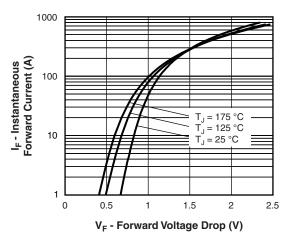


Fig. 1 - Typical Forward Voltage Drop Characteristics

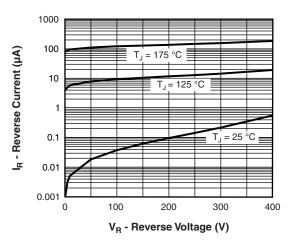


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

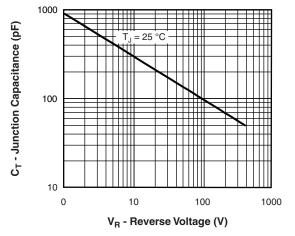


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

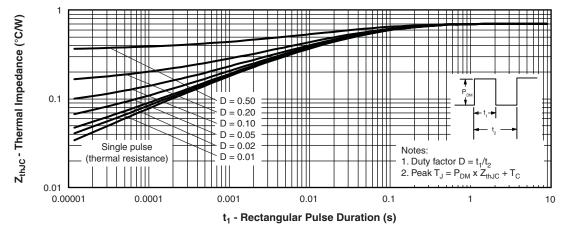


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

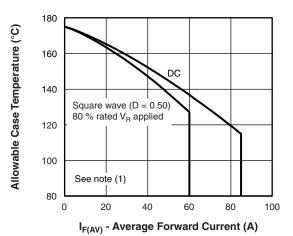


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

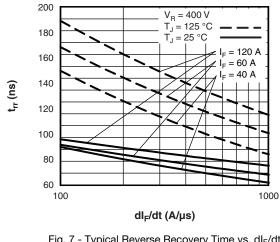


Fig. 7 - Typical Reverse Recovery Time vs. dl_E/dt

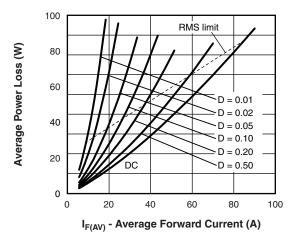


Fig. 6 - Forward Power Loss Characteristics

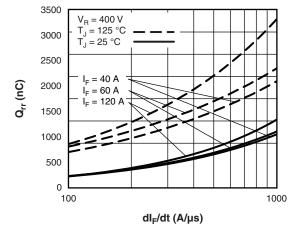


Fig. 8 - Typical Stored Charge vs. dl_E/dt

Note

⁽¹⁾ Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$; Pd = Forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6); Pd_{REV} = Inverse power loss = $V_{R1} \times I_R$ (1 - D); I_R at V_{R1} = 80 % rated V_R

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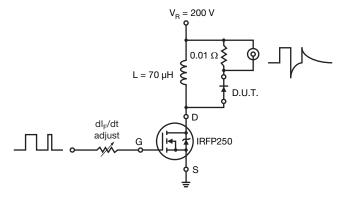
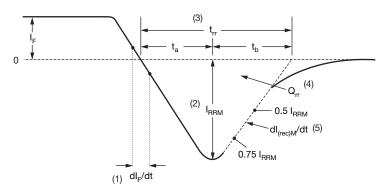


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dI_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_F$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

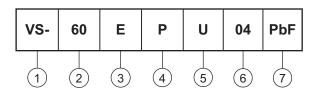
(5) $dI_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

- Current rating (60 = 60 A)

3 - Circuit configuration:

• E = single diode

• A = single diode, 3 pins

4 - Package:

P = TO-247AC (modified)

5 - Type of silicon:

U = ultrafast recovery

6 - Voltage rating (04 = 400 V)

7 - Environmental digit:

PbF = lead (Pb)-free and RoHS-compliant

-N3 = halogen-free, RoHS-compliant and totally lead (Pb)-free

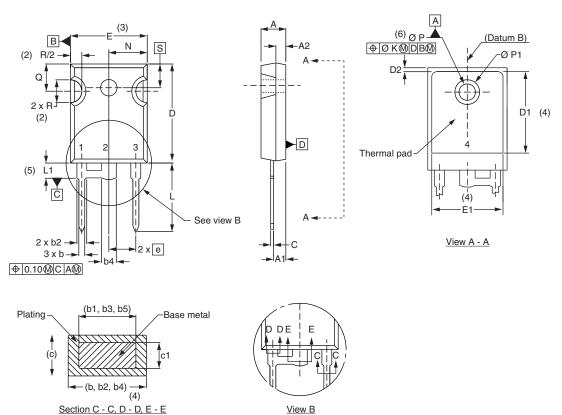
ORDERING INFORMATION (Example)									
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION						
VS-60EPU04PbF	25	500	Antistatic plastic tube						
VS-60EPU04-N3	25	500	Antistatic plastic tube						
VS-60APU04PbF	25	500	Antistatic plastic tube						
VS-60APU04-N3	25	500	Antistatic plastic tube						

LINKS TO RELATED DOCUMENTS							
Dimensions	TO-247AC modified	www.vishay.com/doc?95541					
	TO-247AC	www.vishay.com/doc?95542					
	TO-247AC modified PbF	www.vishay.com/doc?95255					
Dort marking information	TO-247AC modified -N3	www.vishay.com/doc?95442					
Part marking information	TO-247ACPbF	www.vishay.com/doc?95226					
	TO-247AC-N3	www.vishay.com/doc?95007					

Vishay Semiconductors

TO-247 - 50 mils L/F modified

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	IETERS	INC	HES	NOTES		SYMB		
STINIBUL	MIN.	MAX.	MIN.	MAX.	NOTES		STIVID		
Α	4.65	5.31	0.183	0.209			D2		
A1	2.21	2.59	0.087	0.102			Е		
A2	1.17	1.37	0.046	0.054			E1		
b	0.99	1.40	0.039	0.055			е		
b1	0.99	1.35	0.039	0.053			ØK		
b2	1.65	2.39	0.065	0.094			L		
b3	1.65	2.34	0.065	0.092			L1		
b4	2.59	3.43	0.102	0.135			N		
b5	2.59	3.38	0.102	0.133			ØΡ		
С	0.38	0.89	0.015	0.035			Ø P1		
c1	0.38	0.84	0.015	0.033			Q		
D	19.71	20.70	0.776	0.815	3		R		
D1	13.08	-	0.515	-	4		S		

SYMBOL	MILLIN	IETERS	INC	INCHES			
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES		
D2	0.51	1.35	0.020	0.053			
Е	15.29	15.87	0.602	0.625	3		
E1	13.46	-	0.53	-			
е	5.46 BSC		0.215	BSC			
ØK	0.254		0.0)10			
L	14.20	16.10	0.559	0.634			
L1	3.71	4.29	0.146	0.169			
Ν	7.62	BSC	0				
ØΡ	3.56	3.66	0.14	0.144			
Ø P1	-	7.39	-	0.291			
Q	5.31	5.69	0.209	0.224			
R	4.52	5.49	0.178	0.216			
S	5.51	BSC	0.217	BSC			

Notes

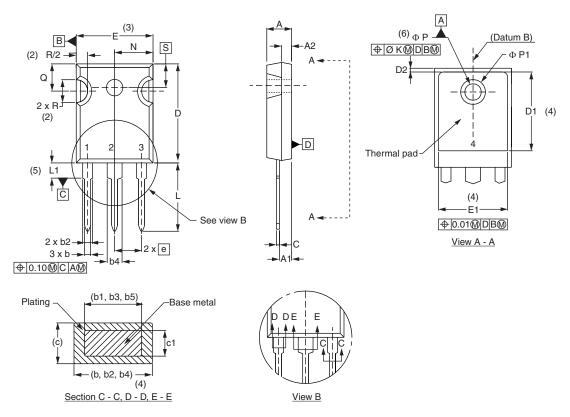
- (1) Dimensioning and tolerance per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension c and Q



Vishay Semiconductors

TO-247 - 50 mils L/F

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	IETERS	INC	HES	NOTES	SYMBOL	MILLIM	IETERS	INC	HES	NOTES	
STIMBOL	MIN.	MAX.	MIN.	MAX.	NOTES		STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.65	5.31	0.183	0.209			D2	0.51	1.35	0.020	0.053	
A1	2.21	2.59	0.087	0.102			E	15.29	15.87	0.602	0.625	3
A2	1.17	1.37	0.046	0.054			E1	13.46	=.	0.53	-	
b	0.99	1.40	0.039	0.055			е	5.46	BSC	0.215	BSC	
b1	0.99	1.35	0.039	0.053			ØK	0.2	254	0.0	10	
b2	1.65	2.39	0.065	0.094			L	14.20	16.10	0.559	0.634	
b3	1.65	2.34	0.065	0.092			L1	3.71	4.29	0.146	0.169	
b4	2.59	3.43	0.102	0.135			N	7.62	BSC	0	.3	
b5	2.59	3.38	0.102	0.133			ØΡ	3.56	3.66	0.14	0.144	
С	0.38	0.89	0.015	0.035			Ø P1	ı	7.39	-	0.291	
c1	0.38	0.84	0.015	0.033			Q	5.31	5.69	0.209	0.224	
D	19.71	20.70	0.776	0.815	3		R	4.52	5.49	0.178	0.216	
D1	13.08	-	0.515	-	4		S	5.51	BSC	0.217	BSC	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
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Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.

Revision: 02-Oct-12 Document Number: 91000